

RF SWITCH CG2179M2

L, S-band Medium Power SPDT Switch

DESCRIPTION

The CG2179M2 is a pHEMT GaAs SPDT (<u>Single Pole Double Throw</u>) switch. This device can operate from 0.05 GHz to 3.0GHz, having low insertion loss and high isolation.

FEATURES

- Control voltage:
 VC(H) = 1.8 to 5.3 V (3.0 V TYP.)
 VC(L) = -0.2 to 0.2 V (0 V TYP.)
- Low insertion loss :

 $\begin{array}{l} L_{ins}1 = 0.30 \text{ dB TYP.} @ f = 0.05 \text{ to } 0.5 \text{ GHz} \\ L_{ins}2 = 0.30 \text{ dB TYP.} @ f = 0.5 \text{ to } 1.0 \text{ GHz} \\ L_{ins}3 = 0.40 \text{ dB TYP.} @ f = 1.0 \text{ to } 2.0 \text{ GHz} \\ L_{ins}4 = 0.45 \text{ dB TYP.} @ f = 2.0 \text{ to } 2.5 \text{ GHz} \\ L_{ins}5 = 0.45 \text{ dB TYP.} @ f = 2.5 \text{ to } 3.0 \text{ GHz} \end{array}$

High isolation :

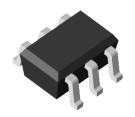
ISL1 = 39 dB TYP. @ f = 0.05 to 0.5 GHz ISL2 = 33 dB TYP. @ f = 0.5 to 1.0 GHz ISL3 = 27 dB TYP. @ f = 1.0 to 2.0 GHz ISL4 = 26 dB TYP. @ f = 2.0 to 2.5 GHz ISL5 = 23 dB TYP. @ f = 2.5 to 3.0 GHz

Power handling :

$$\begin{split} P_{in(0.5dB)} = +32 \text{ dBm TYP. } & @ \text{ } f = 3.0 \text{ GHz}, \\ VC(H) = 3.0 \text{ } V, \text{ } VC(L) = 0 \text{ } V \end{split}$$

PACKAGE

6-pin mini mold Package
 (2.0mm x 1.25mm x 0.9mm)



APPLICATIONS

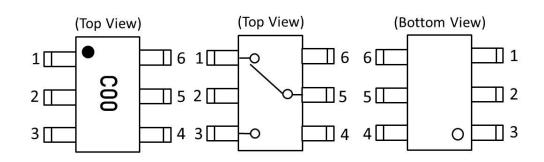
Wireless LAN (IEEE 802.11 b/g/n/ac)

ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Description
CG2179M2	CG2179M2-C4	6-pin mini mold package (Pb-Free)	C00	 Embossed tape 8 mm wide Pin 4, 5, 6 face the perforation side of the tape MOQ 10 kpcs/reel
CG2179M2-EVAL	CG2179M2-EVAL			 Evaluation Board with DC block capacitors, power supply bypass capacitors, and RF and DC connectors MOQ 1



PIN CONFIGURATION AND INTERNAL BLOCK DIAGRAM



Pin No.	Pin Name
1	RF1
2	GND
3	RF2
4	VC2
5	RFC
6	VC1

TRUTH TABLE

VC1	VC2	RFC-RF1	RFC-RF2
Low	High	ON	OFF
High	Low	OFF	ON

ABSOLUTE MAXIMUM RATINGS

(TA = +25°C, unless otherwise specified)

Parameter	Symbol	Rating	Unit
Control Voltage	VC	6.0 ^{Note 1}	V
Input Power	P _{in} 1	+33 ^{Note 2}	dBm
	P _{in} 2	+29 ^{Note 3}	dBm
Operating Ambient Temperature	T _A	-45 ~ + 85	°C
Storage Temperature	T_{stg}	-55 ~ + 150	°C

- **Note** 1. $|VC1 VC2| \le 6.0V$
 - 2. $3.0V \le |VC1 VC2| \le 5.0V$, $0.4GHz \le f$
 - 3. $3.0V \le |VC1 VC2| \le 5.0V$, $0.05GHz \le f \le 0.4GHz$

RECOMMENDED OPERATING RANGE

(TA = +25°C, unless otherwise specified)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Operating Frequency	f	0.05	-	3.0	GHz
Switch Control Voltage (H)	VC(H)	+1.8	+3.0	+5.3	V
Switch Control Voltage (L)	VC(L)	-0.2	0	+0.2	V



ELECTRICAL CHARACTERISTICS 1

 $(TA = +25^{\circ}C, VC(H) = 3.0V, VC(L) = 0V, Zo = 50\Omega, DC Block Capacitance = 56pF, unless otherwise specified)$

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Insertion Loss	L _{INS} 1	f=0.05 to 0.5GHz Note 1	-	0.30	0.50	dB
	L _{INS} 2	f=0.5 to 1.0GHz	-	0.30	0.50	dB
	L _{INS} 3	f=1.0 to 2.0GHz	-	0.40	0.60	dB
	L _{INS} 4	f=2.0 to 2.5GHz	-	0.45	0.65	dB
	L _{INS} 5	f=2.5 to 3.0GHz	-	0.45	0.65	dB
Isolation	ISL1	f=0.05 to 0.5GHz Note 1	36	39	-	dB
	ISL2	f=0.5 to 1.0GHz	30	33	-	dB
	ISL3	f=1.0 to 2.0GHz	23	27	-	dB
	ISL4	f=2.0 to 2.5GHz	22	26	-	dB
	ISL5	f=2.5 to 3.0GHz	21	24	-	dB
Return Loss	RL	f=0.05 to 3.0GHz Note 1	15	20	-	dB
0.1dB Loss Compression Input	P _{in(0.1dB)}	f=0.05~0.5GHz Note 1	-	+26	-	dBm
Power Note 2		f=0.5~3.0GHz	-	+30	-	dBm
0.5dB Loss Compression Input	P _{in(0.5dB)}	f=0.05~0.5GHz Note 1	-	+28.5	-	dBm
Power Note 3		f=0.5~3.0GHz	-	+32	-	dBm
2nd Harmonics	2f0	f=3.0GHz, P _{in} =+20dBm	-	-85	-	dBc
3rd Harmonics	3f0	f=3.0GHz, P _{in} =+20dBm	-	-85	-	dBc
3rd Order Input Intercept Point	IIP ₃	f=2.5GHz, 2-tone 1MHz Spacing	-	+58	-	dBm
Error Vector Magnitude	EVM	802.11g, 64QAM, 54Mbps Pin≦+25dBm	-	2.5	-	%
Switch Control Current	I _{CONT}	RF none	-	1	10	uA
Switching Speed	t _{SW}	50% CTL to 90/10% RF	-	50	-	ns

Note 1. DC block capacitance = 1000pF at f=0.05 to 0.5GHz

^{2.} $P_{in(0.1dB)}$ is the measured input power level when the insertion loss increases 0.1dB more than that of the linear range.

^{3.} $P_{in(0.5dB)}$ is the measured input power level when the insertion loss increases 0.5dB more than that of the linear range



ELECTRICAL CHARACTERISTICS 2

 $(TA = +25^{\circ}C, VC(H) = 1.8V, VC(L) = 0V, Zo = 50\Omega, DC Block Capacitance = 56pF, unless otherwise specified)$

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Insertion Loss	L _{INS} 1	f=0.05 to 0.5GHz Note 1	-	0.30	0.50	dB
	L _{INS} 2	f=0.5 to 1.0GHz	-	0.30	0.50	dB
	L _{INS} 3	f=1.0 to 2.0GHz	-	0.40	0.60	dB
	L _{INS} 4	f=2.0 to 2.5GHz	-	0.45	0.65	dB
	L _{INS} 5	f=2.5 to 3.0GHz	-	0.45	0.65	dB
Isolation	ISL1	f=0.05 to 0.5GHz Note 1	36	39	-	dB
	ISL2	f=0.5 to 1.0GHz	30	33	-	dB
	ISL3	f=1.0 to 2.0GHz	23	27	-	dB
	ISL4	f=2.0 to 2.5GHz	22	26	-	dB
	ISL5	f=2.5 to 3.0GHz	21	24	-	dB
Return Loss	RL	f=0.05 to 3.0GHz Note 1	15	20	-	dB
0.1dB Loss Compression Input	P _{in(0.1dB)}	f=0.05~0.5GHz Note 1	-	+19	-	dBm
Power Note 2		f=0.5~3.0GHz	-	+23	-	dBm
0.5dB Loss Compression Input	P _{in(0.5dB)}	f=0.05~0.5GHz Note 1	-	+22	-	dBm
Power Note 3		f=0.5~3.0GHz	-	+26	-	dBm
Switch Control Current	I _{CONT}	RF none	-	1	10	uA
Switching Speed	t _{SW}	50% CTL to 90/10% RF	-	50	-	ns

Note 1. DC block capacitance = 1000pF at f=0.05 to 0.5GHz

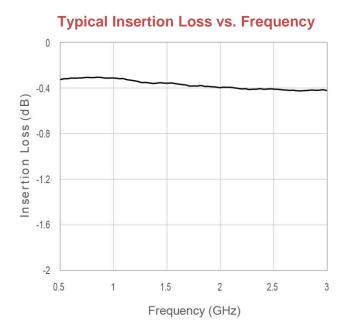
^{2.} P_{in(0.1dB)} is the measured input power level when the insertion loss increases 0.1dB more than that of the linear range.

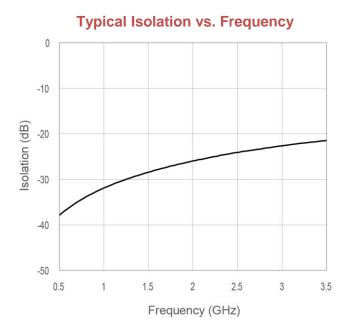
^{3.} $P_{in(0.5dB)}$ is the measured input power level when the insertion loss increases 0.5dB more than that of the linear range

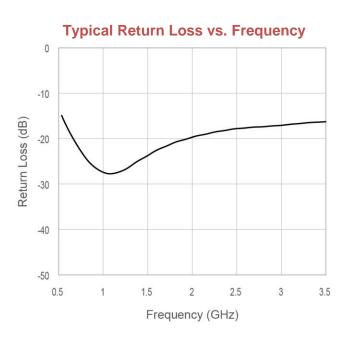


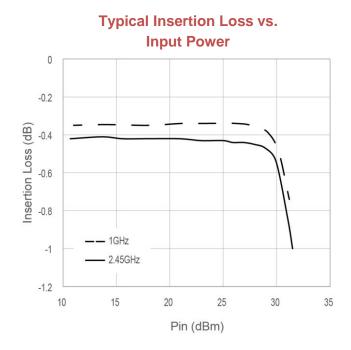
TYPICAL CHARACTERISTICS

(Vc(H)=3V, Vc(L)=0V, TA= +25°C, DC Block Capacitance=56pF, through board loss is subtracted in insertion loss data)



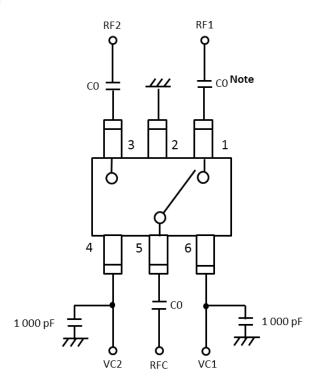








EVALUATION CIRCUIT

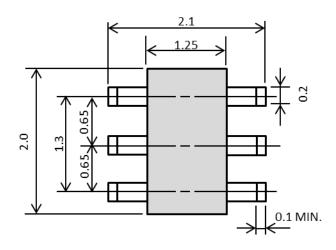


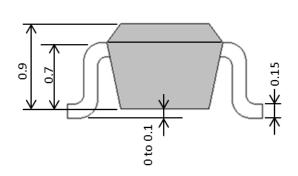
Note C0: 0.05 to 0.5 GHz 1000pF: 0.4 to 3.0 GHz 56pF

The application circuits and their parameters are for reference only and are not intended for use in actual designs. DC Blocking Capacitors are required at all RF ports.

PACKAGE DIMENSIONS

6-pin mini mold package (Unit: mm)

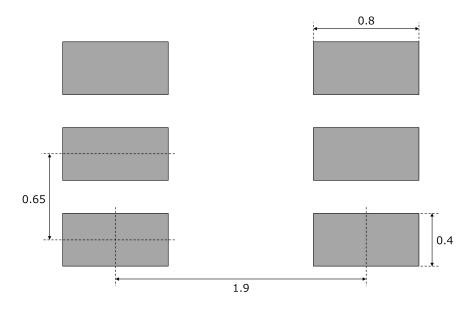






PCB LAYOUT FOOTPRINT

6-pin mini mold (unit: mm)



The PCB Layout Footprint in this document is for reference only

RECOMMENDED SOLDERING CONDITIONS

Recommended Soldering Conditions are available on CEL's Part Summary page under Associated Documents



REVISION HISTORY

Version	Change to current version	Page(s)
CDS-0008-03 (Issue A) February 17, 2016	Initial datasheet	N/A
CDS-0008-03 (Issue B)	Added Eval Board ordering information	1, 2
March 24, 2016	Updated Marking information	
CDS-0008-03 (Issue C) August 11, 2016	Removed "Preliminary"	All
CDS-0008-03 (Issue D) January 11, 2017	Revised Electrical Characteristics table Added "Recommended Soldering Conditions" section	3, 5
CDS-0008-03 (Issue E) May 24, 2017	Updated Evaluation Circuit output pinouts - switched RF1 and RF2	4
CDS-0008-04 (Issue F) June 13, 2017	Added power handling @0.05GHz to 0.5GHz Added absolute maximum rating @0.05GHz≦f≦0.4GHz Revised recommended operating switch control voltage Updated Electrical Characteristics table and added a second Electrical characteristics table on page 4	1,2,3,4
CDS-0008-05 (Issue G) June 20, 2017	Added Error Vector Magnitude parameter to Electrical Characteristics table 1	3
CDS-0008-06 (Issue H) August 29, 2017	Updated Applications section Added "Typical Characteristics" graphs section	1, 5
CDS-0008-07 (Issue I) April 12, 2019	Added PCB Layout Footprint section	7



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- Do not chemically make gas or powder with this product.
- When discarding this product, please obey the laws of your country.
- Do not lick the product or in any way allow it to enter the mouth.

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